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Standards

Irish Standard
I.S. EN 60191-6-18:2010

Mechanical standardization of semiconductor devices - Part 6-18: General rules for the preparation of outline drawings of surface mounted semiconductor device packages - Design guide for ball grid array (BGA)

I.S. EN 60191-6-18:2010

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EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN 60191-6-18

February 2010

ICS 31.080.01

English version

**Mechanical standardization of semiconductor devices -
Part 6-18: General rules for the preparation of outline drawings
of surface mounted semiconductor device packages -
Design guide for ball grid array (BGA)
(IEC 60191-6-18:2010)**

Normalisation mécanique
des dispositifs à semiconducteurs -
Partie 6-18: Règles générales
pour la préparation des dessins
d'encombrement des dispositifs
à semiconducteurs
pour montage en surface -
Guide de conception pour les boîtiers
matriciels à billes (BGA)
(CEI 60191-6-18:2010)

Mechanische Normung
von Halbleiterbauelementen -
Teil 6-18: Allgemeine Regeln
für die Erstellung
von Gehäusezeichnungen
von SMD-Halbleitergehäusen -
Konstruktionsleitfaden
für Ball-Grid-Array (BGA)
(IEC 60191-6-18:2010)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: Avenue Marnix 17, B - 1000 Brussels

Foreword

The text of document 47D/753A/FDIS, future edition 1 of IEC 60191-6-18, prepared by SC 47D, Mechanical standardization for semiconductor devices, of IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60191-6-18 on 2010-02-01.

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at national level by publication of an identical
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Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 60191-9-18:2010 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

- | | | |
|---------------|------|-----------------------------|
| IEC 60191-6-2 | NOTE | Harmonized as EN 60191-6-2. |
| IEC 60191-6-4 | NOTE | Harmonized as EN 60191-6-4. |
| IEC 60191-6-5 | NOTE | Harmonized as EN 60191-6-5. |
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Annex ZA
(normative)**Normative references to international publications
with their corresponding European publications**

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
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INTERNATIONAL STANDARD

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**Normalisation mécanique des dispositifs à semiconducteurs –
Partie 6-18: Règles générales pour la préparation des dessins d'encombrement
des dispositifs à semiconducteurs pour montage en surface – Guide de
conception pour les boîtiers matriciels à billes (BGA)**





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